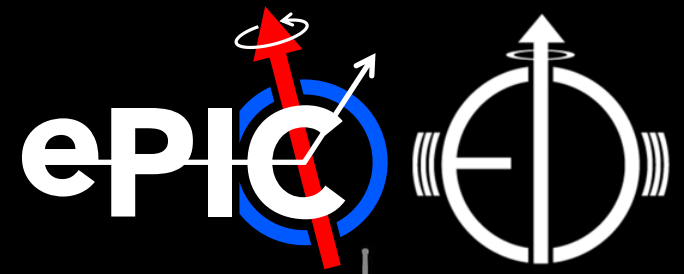




UNIVERSITY OF
BIRMINGHAM

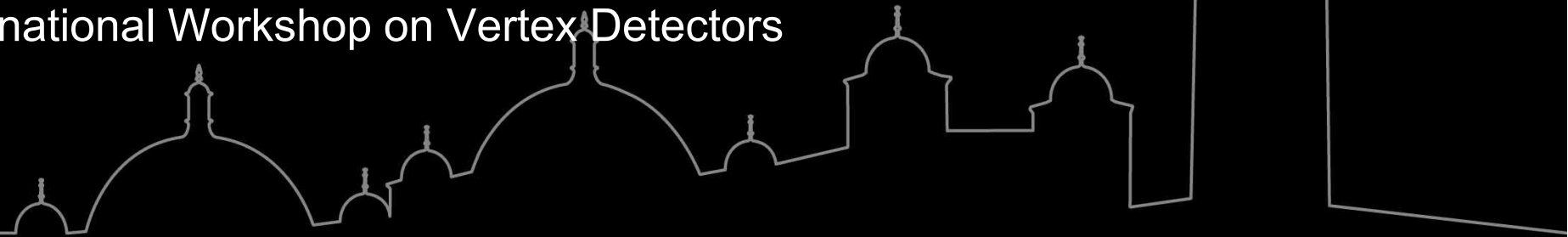


EIC vertex and tracking detector

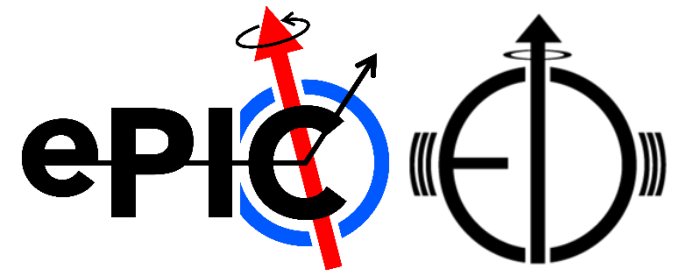
James Glover
(on behalf of the ePIC SVT subdetector collaboration)

VERTEX 2025: 33rd International Workshop on Vertex Detectors

August 2025



EIC



The facility.

- The EIC is to be built at the [Brookhaven National Laboratory \(BNL\)](#) incorporating the existing Relativistic Heavy Ion Collider.

Overarching science questions.

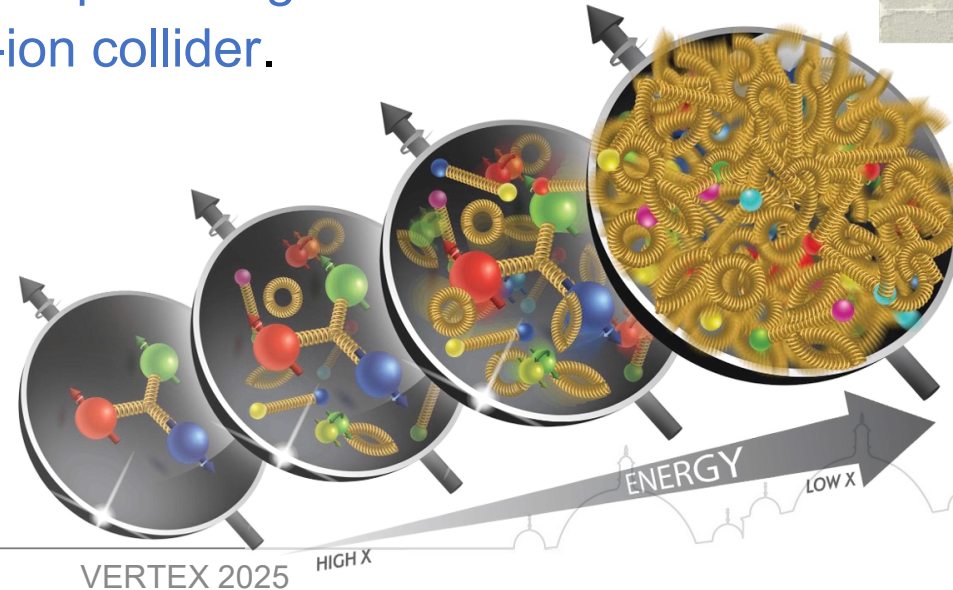
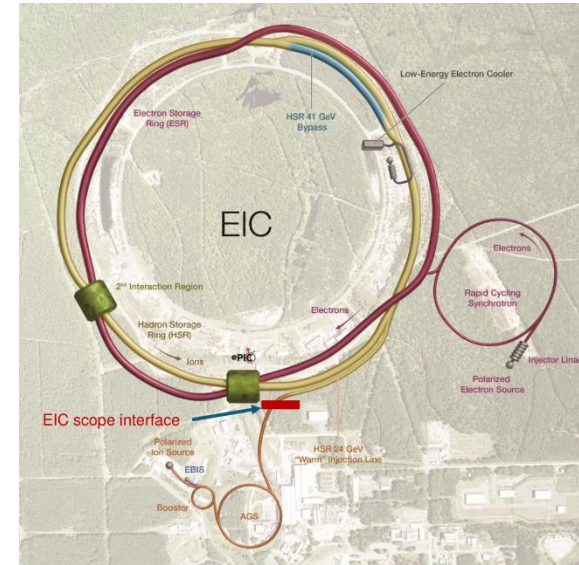
- How does [the mass and spin of the nucleon](#) arise from its constituents?
- What are the emergent [properties of dense systems of gluons](#)?

Uniqueness

- World's first [polarised electron, polarised proton/light-ion collider](#).
- World's first [polarised electron, heavy-ion collider](#).

Timeline

- [Dec 2019: EIC project approved.](#)
- [Dec 2025: EIC project detector TDR.](#)
- 2033 –2035: Transition to operations.

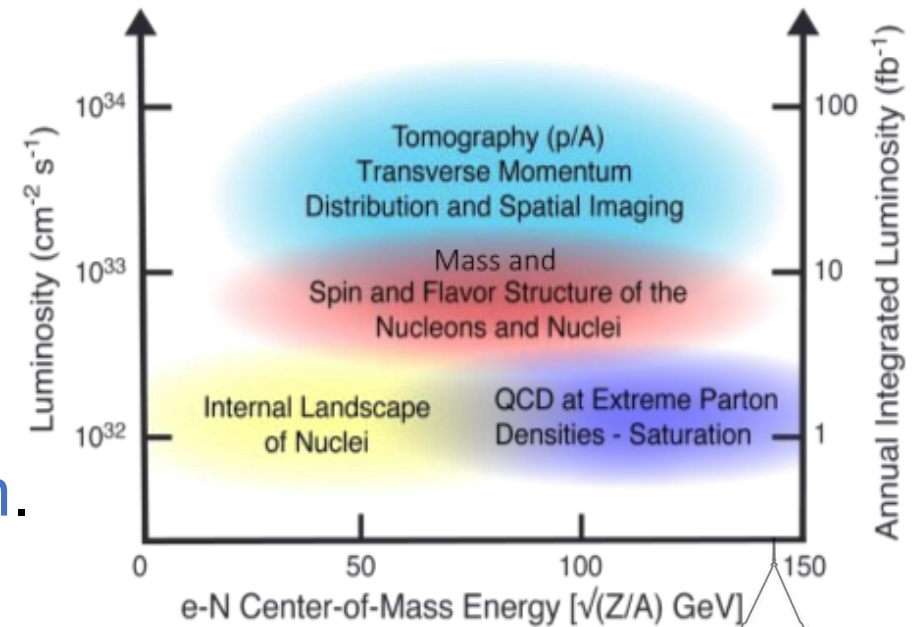
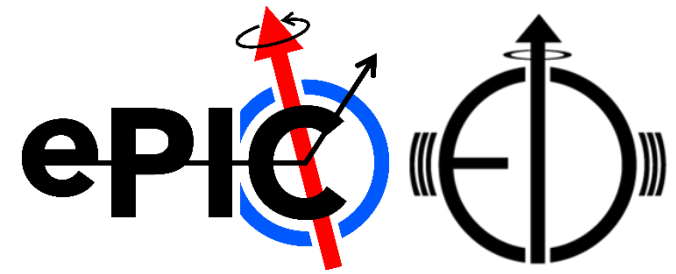


UNIVERSITY OF
BIRMINGHAM

August 2025

Design goals

- High Luminosity: $L = 10^{33} - 10^{34} \text{ cm}^{-2}\text{sec}^{-1}$, 10 – 100 $\text{fb}^{-1}/\text{year}$.
- Center of mass energy: 20 – 100 GeV, upgradable to 140 GeV.
- Highly Polarized Beams: 70%.
- Large Ion Species Range: protons – Uranium.
- Large detector acceptance and good background conditions.
- Accommodate a Second Interaction Region (IR).
 - The EIC Project covers the accelerator and one detector.



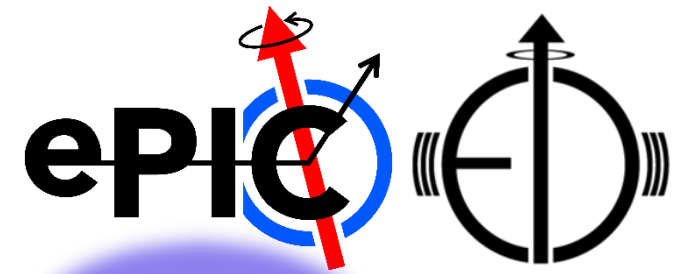
Detector requirements

Internal Landscape of Nuclei

QCD at Extreme Parton Densities Saturation

Mass, Spin, Flavour Structure of the Nucleons and Nuclei

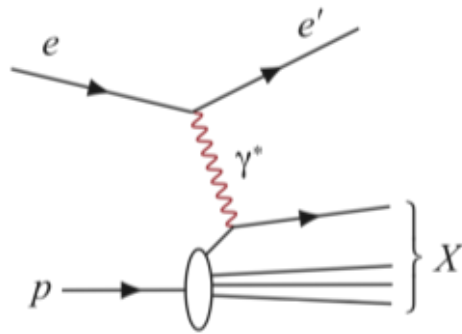
Tomography Transverse Momentum Distribution Spatial Imaging



QCD at Extreme Parton Densities Saturation

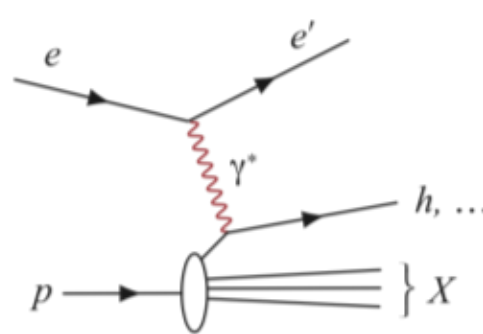
Tomography Transverse Momentum Distribution Spatial Imaging

Inclusive DIS



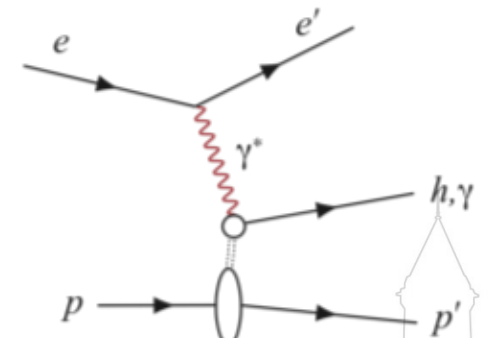
- High performance **electron identification and reconstruction**.

Semi-inclusive DIS



- Tracking and hadronic calorimetry.
- **Heavy flavors identification** from vertexing.
- Light flavors from dedicated **PID** detectors.

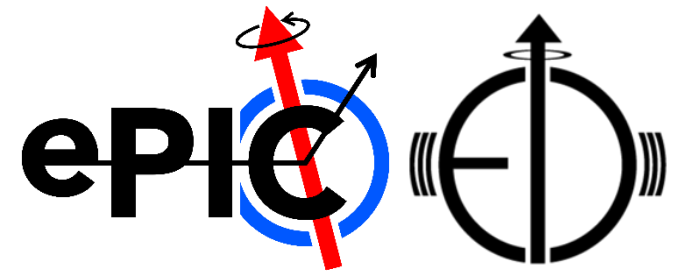
Exclusive DIS



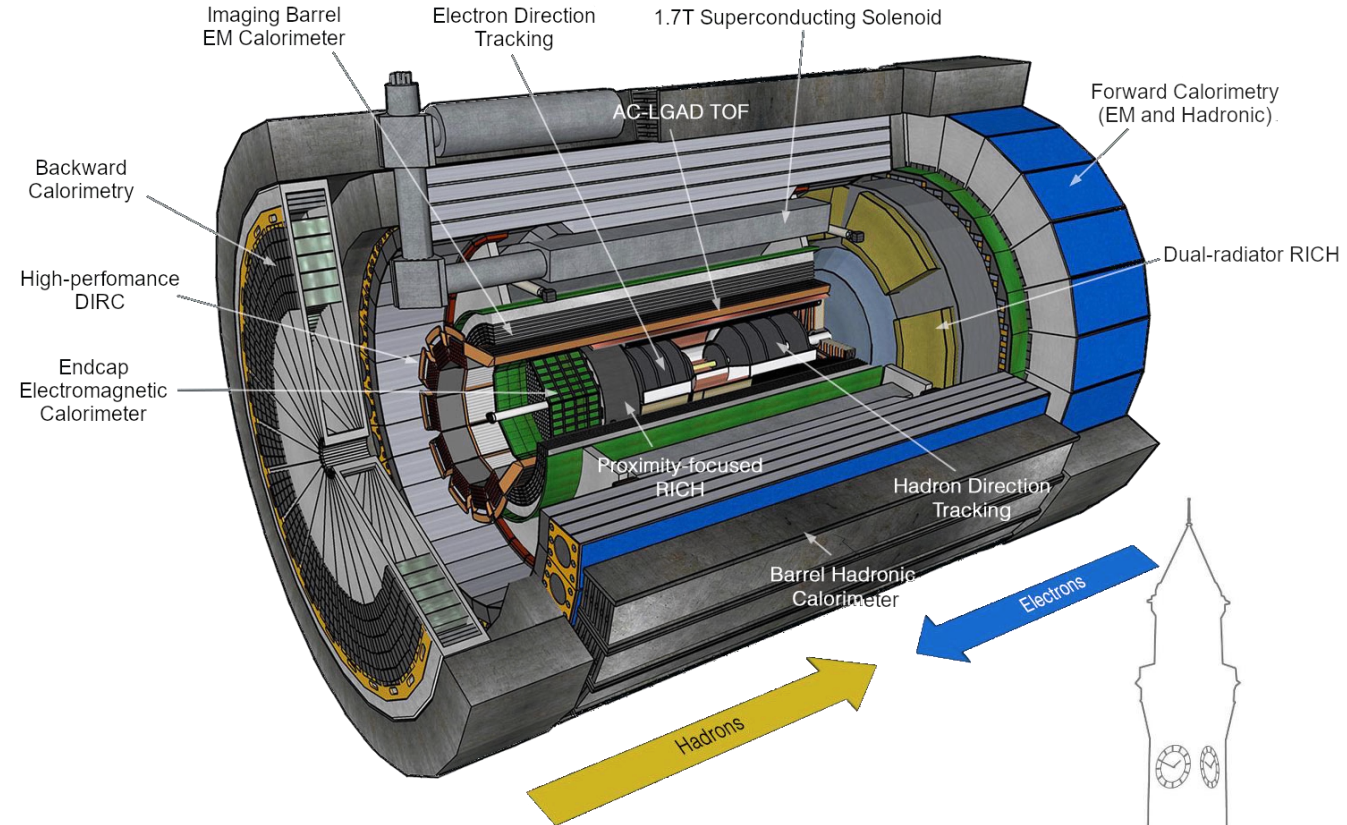
- Efficient **proton tagging**.
- Cover full **acceptance range**.



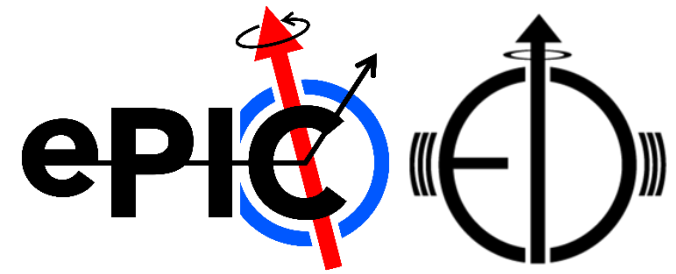
ePIC detector



- Compact central detector.
 - 2.67 m radius and 9.5 m length.
 - Combines **tracking** and **vertexing**, **PID**, and **EM and hadronic calorimetry**.
 - Asymmetric beam energies, different electron and hadron endcaps.
- **1.7 T solenoidal field**.
- Streaming readout approach.
- Extensive **beamline instrumentation** integral to science programme



Tracking requirements



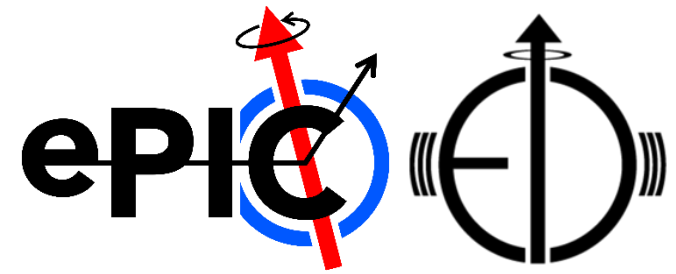
- Physics derived requirements on precise low momentum particle tracking has driven the need for **very high point resolution** and **ultra-low material budget** → most challenging requirements:
 - High granularity, **low power** active element.
 - **Minimal material** from mechanics, cooling, power and data distribution.

| Tracking requirements from PWGs | | | | | | | |
|---------------------------------|---|-------------------|--|---|---|---|---|
| | | | Momentum res. | Material budget | Minimum pT | Transverse pointing res. | |
| η | | | | | | | |
| -3.5 to -3.0 | Central Detector | Backward Detector | $\sigma_{p/p} \sim 0.1\% \times p \oplus 0.5\%$ | ~5% X0 or less | 100-150 MeV/c | dca(xy) ~ 30/pT $\mu\text{m} \oplus 40 \mu\text{m}$ | |
| -3.0 to -2.5 | | | | | 100-150 MeV/c | | |
| -2.5 to -2.0 | | | 100-150 MeV/c | | dca(xy) ~ 30/pT $\mu\text{m} \oplus 20 \mu\text{m}$ | | |
| -2.0 to -1.5 | | | 100-150 MeV/c | | | | |
| -1.5 to -1.0 | | | | | $\sigma_{p/p} \sim 0.05\% \times p \oplus 0.5\%$ | 100-150 MeV/c | |
| -1.0 to -0.5 | | Barrel | $\sigma_{p/p} \sim 0.05\% \times p \oplus 0.5\%$ | | ~5% X0 or less | 100-150 MeV/c | dca(xy) ~ 20/pT $\mu\text{m} \oplus 5 \mu\text{m}$ |
| -0.5 to 0 | | | | | | 100-150 MeV/c | |
| 0 to 0.5 | | | | | | 100-150 MeV/c | |
| 0.5 to 1.0 | | | | | | 100-150 MeV/c | |
| 1.0 to 1.5 | | | | | | 100-150 MeV/c | |
| 1.5 to 2.0 | | | | | | 100-150 MeV/c | |
| 2.0 to 2.5 | | Forward Detector | $\sigma_{p/p} \sim 0.05\% \times p \oplus 1\%$ | | ~5% X0 or less | 100-150 MeV/c | dca(xy) ~ 30/pT $\mu\text{m} \oplus 20 \mu\text{m}$ |
| 2.5 to 3.0 | 100-150 MeV/c | | | | | | |
| 3.0 to 3.5 | $\sigma_{p/p} \sim 0.1\% \times p \oplus 2\%$ | | 100-150 MeV/c | dca(xy) ~ 30/pT $\mu\text{m} \oplus 40 \mu\text{m}$ | | | |
| | | | | 100-150 MeV/c | | dca(xy) ~ 30/pT $\mu\text{m} \oplus 60 \mu\text{m}$ | |

YR Report, Table 11.2



Operational environment



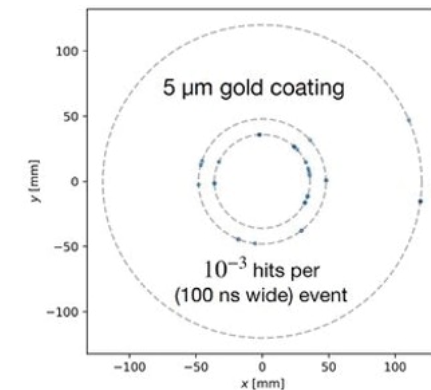
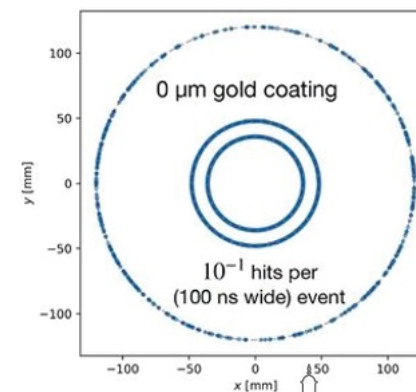
- EIC bunch crossing frequency 98.5 MHz.
 - Interaction frequency orders of magnitude lower.
- Rates for DIS e+p events up to 500 kHz.

| | | | | | |
|--|--------|---------|----------|----------|----------|
| Beam energy [GeV] | 5 x 41 | 5 x 100 | 10 x 100 | 10 x 275 | 18 x 275 |
| L [$10^{33}\text{cm}^{-2}\text{s}^{-1}$] | 0.44 | 3.68 | 4.48 | 10 | 1.54 |
| DIS ep rate [kHz] | 12.5 | 129 | 184 | 500 | 83 |

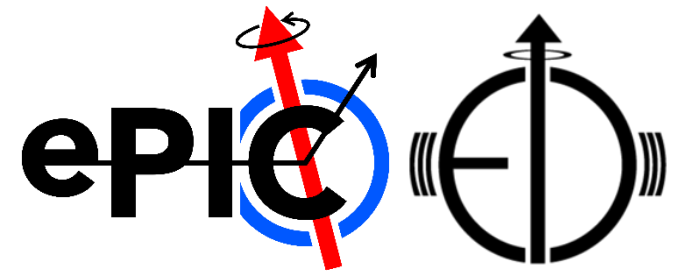
[EIC Conceptual Design Report, Table 3.3](#)

- Up to $\mathcal{O}(\text{GHz})$ rate for background events.
 - Hadron and electron beam gas event rate lowers with improving vacuum condition.
 - Synchrotron radiation reduced of two orders of magnitude with 5 μm gold coating of the beam pipe.
- Manageable readout frame rate.

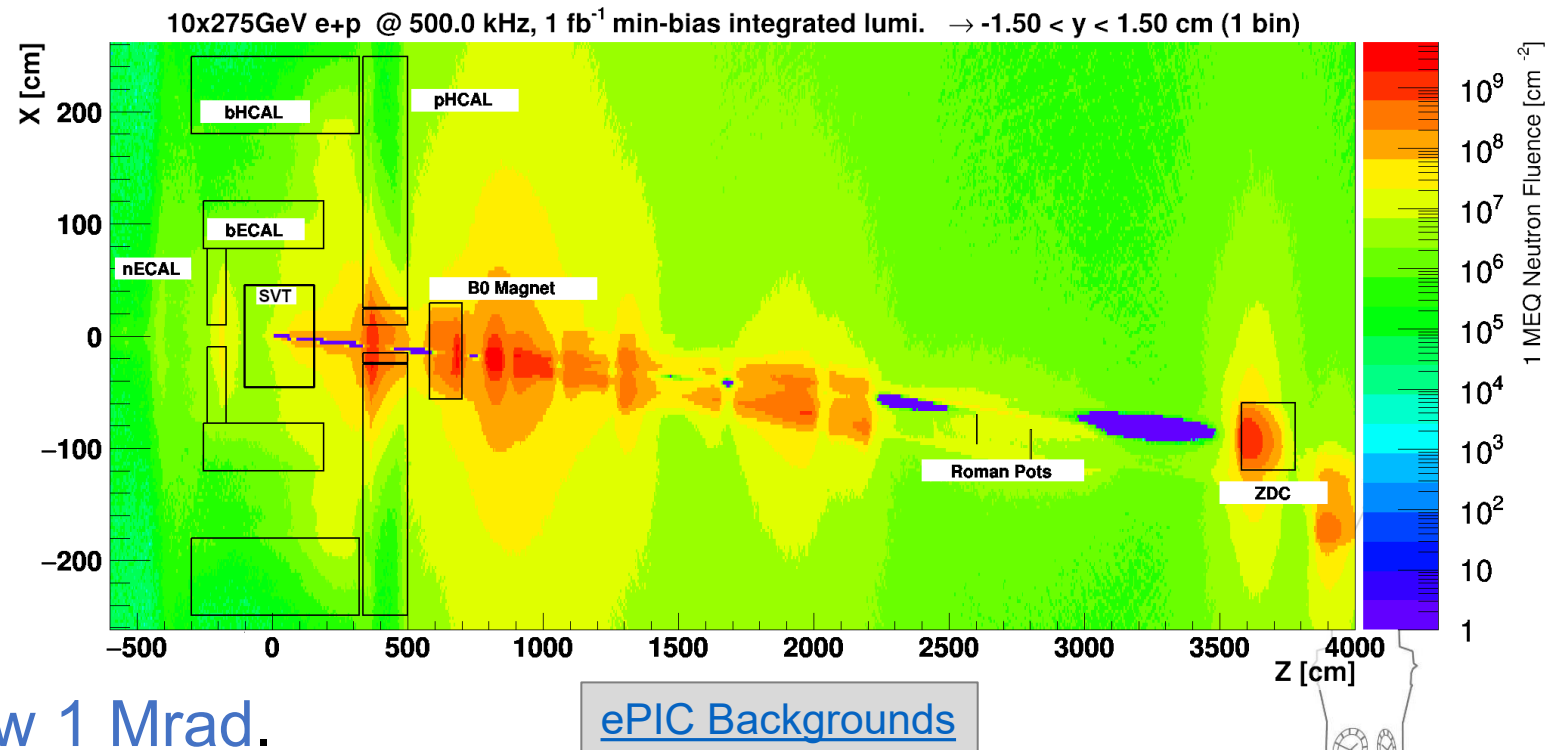
Scatter plots of SR hits in the innermost silicon tracker layers.



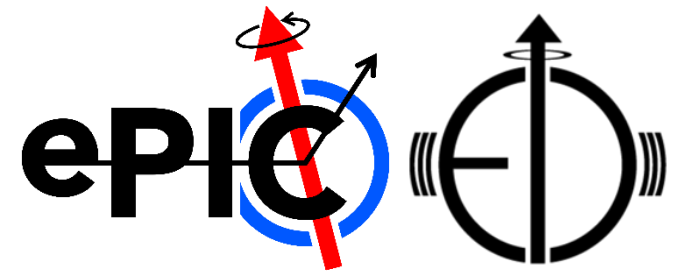
Operational environment



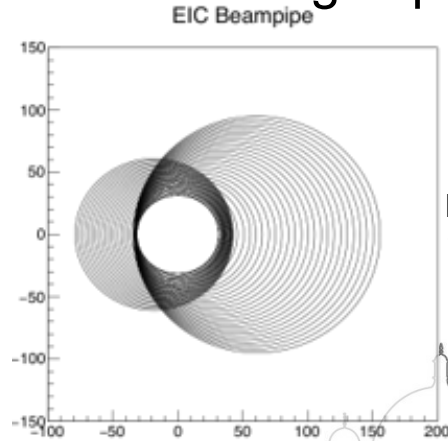
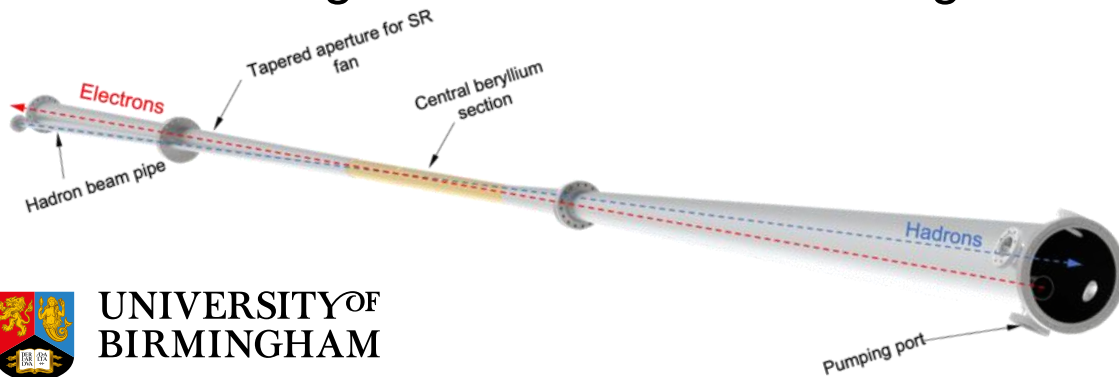
- Low-moderate radiation levels.
 - Much lower radiation fluxes than LHC, widens technology options.
- 10×275 GeV DIS e+p, top luminosity ($1 \times 10^{34} \text{ cm}^{-2}\text{s}^{-1}$).
 - Total Ionising Dose below 1 Mrad.
 - Neutron fluence below $1 \times 10^{10} \text{ n}_{\text{eq}}/\text{cm}^2$.



Integration constraints



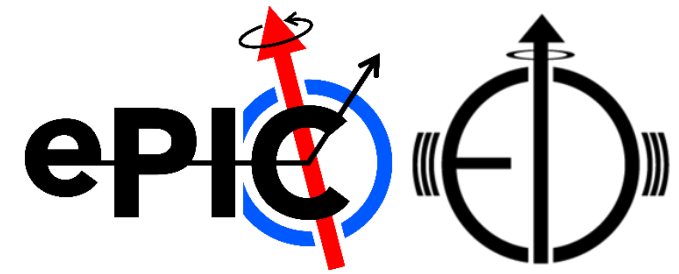
- Large beam pipe diameter, **33 mm radius**; (more) challenging to reach required vertexing precision.
- **Beam pipe diameter increases** away from the interaction point.
 - Silicon tracker to be built in two halves clamped around the beam pipe
 - Divergence already in silicon tracker envelop.
 - **Complex mechanical support design (local and global) and integration procedure.**
- **Beam pipe bake-out** performed with silicon tracker in situ.
 - **Demanding cooling requirements** to maximise vertexing capability and acceptance at large eta within material budget.



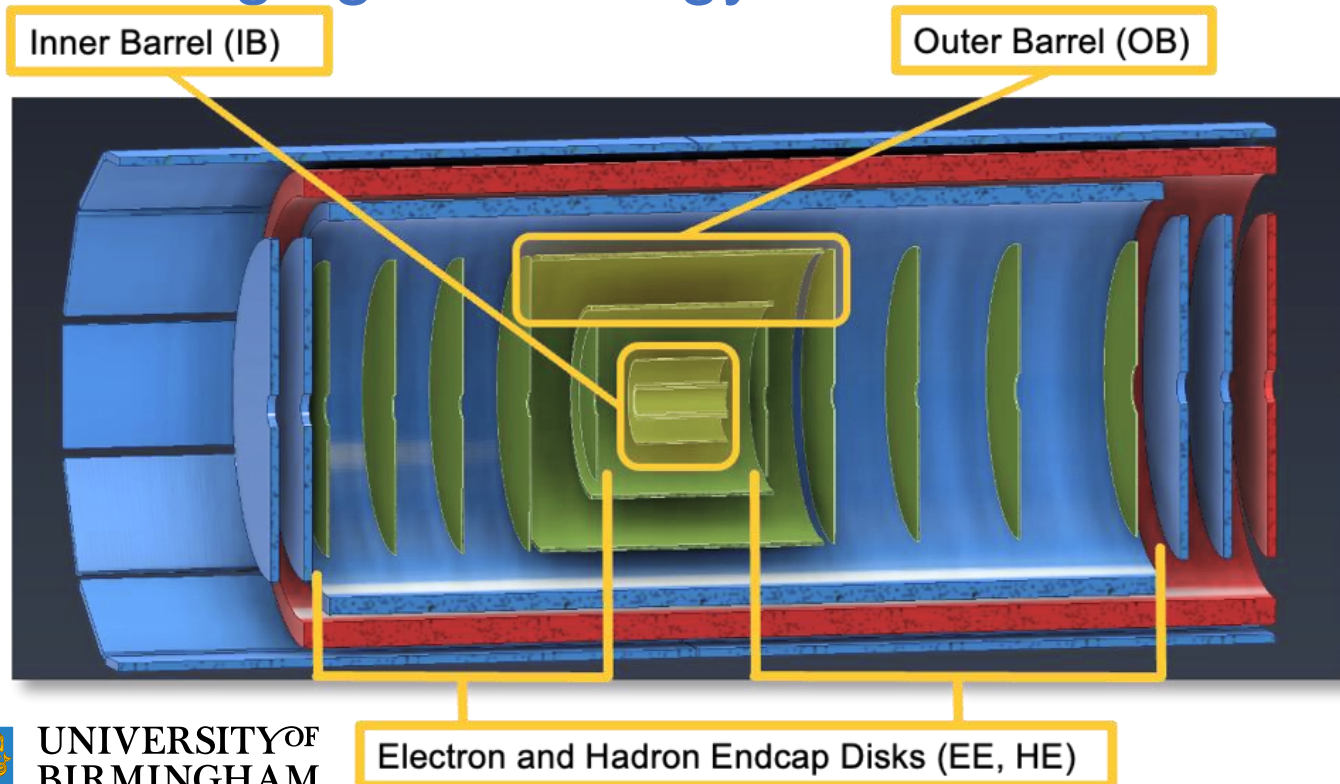
Beampipe profile;
100 mm steps



ePIC silicon vertex tracker (SVT)

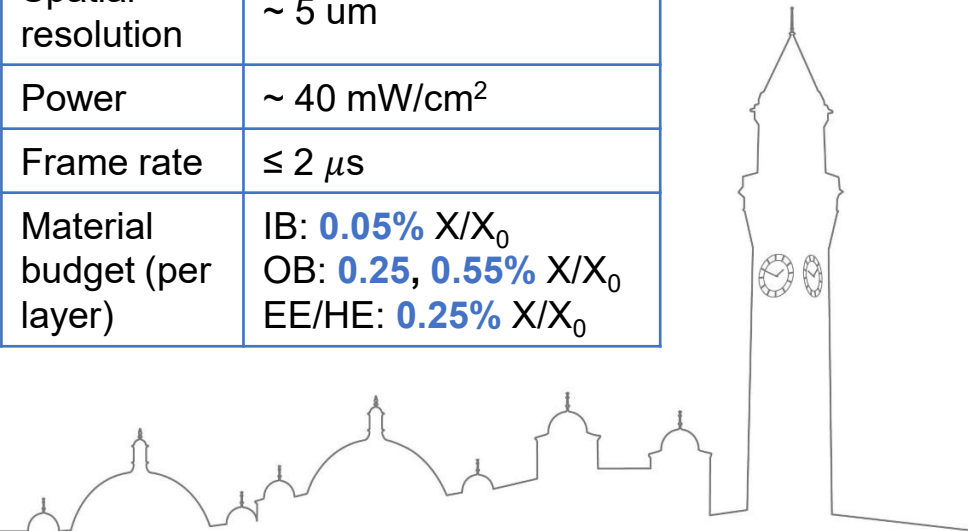


- Well integrated, large acceptance, high precision Silicon Vertex Tracker based on large area, low power MAPS in 65 nm CMOS imaging technology.

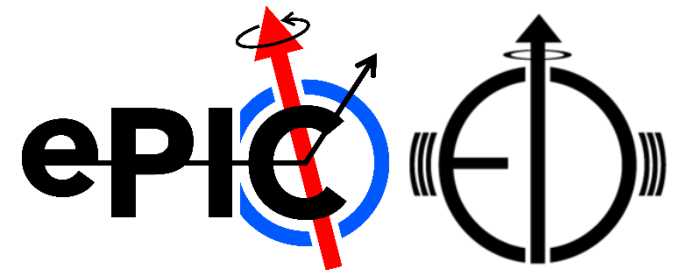


SVT total (active) area: $\sim 8.5 \text{ m}^2$

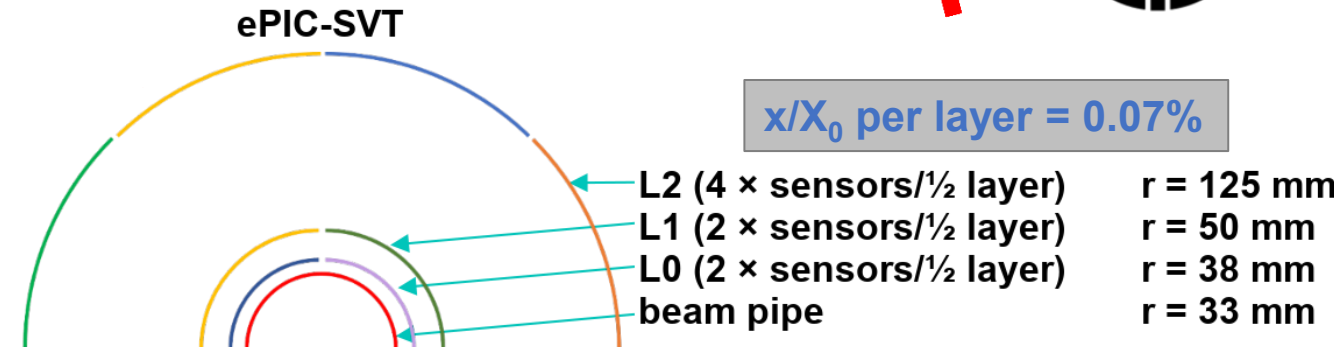
| ePIC SVT target specifications | |
|--------------------------------|---|
| Spatial resolution | $\sim 5 \text{ } \mu\text{m}$ |
| Power | $\sim 40 \text{ mW/cm}^2$ |
| Frame rate | $\leq 2 \text{ } \mu\text{s}$ |
| Material budget (per layer) | IB: $0.05\% X/X_0$ OB: $0.25, 0.55\% X/X_0$ EE/HE: $0.25\% X/X_0$ |



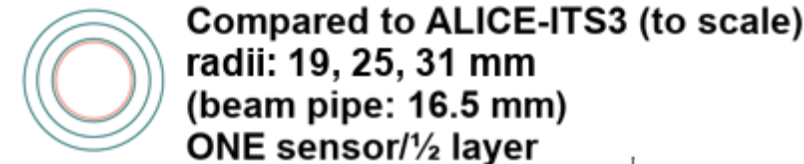
Inner barrel



- Transverse pointing resolution is multiple scattering dominated.
- The IB will adopt the ALICE ITS3 wafer scale sensor and ultra-thin detector concept.



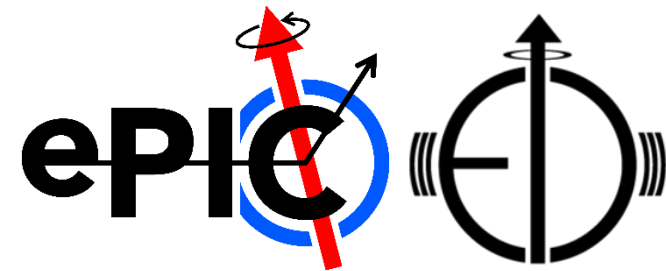
- Three layers of thin, bent, silicon sensors.
- Minimal mechanical support, air cooling, no services in active area.



- Layers positioned to optimise transverse pointing resolution within operational constraints.
 - L0, L1: large beam pipe diameter, beam pipe bake-out (5 mm clearance), sensor width.
 - L2: $r = 125$ mm, dual purpose vertexing & sagitta layer, without increase in material.

| IB | MOSAIX /sensor | Diced W (mm) | Diced L (mm) |
|----|----------------|--------------|--------------|
| L0 | 3 | 58.7 | 266 |
| L1 | 4 | 78.3 | 266 |
| L2 | 5 | 97.8 | 266 |

The sensors



Two variations of the same stitched, repeated sensor unit (RSU).

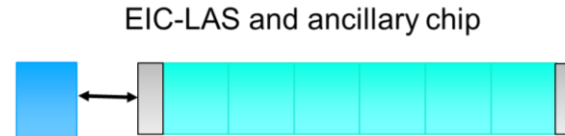
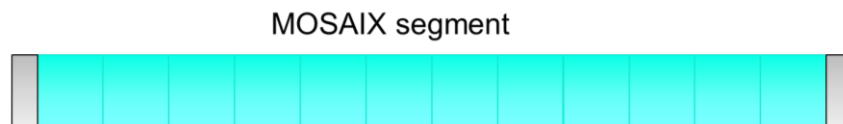
RSU = $21.67 \times 19.56 \text{ mm}^2$, array of $22.8 \times 20.8 \text{ }\mu\text{m}^2$ pixels.

MOSAIX

- To be used for the IB layers (L0-2).
- Same sensor as for ALICE ITS3.

EIC-LAS

- To be used for the OB layers (L3-4) and the endcap disks (ED0-4, HD0-4).
- Modified version of MOASIX, specifically for EIC.



- 12 RSUs. Improve yield and coverage
- 8 data links. Lower material budget
- 7 slow control links. Lower material budget, fit integration requirements
- Direct powering Lower material budget, fit integration requirements

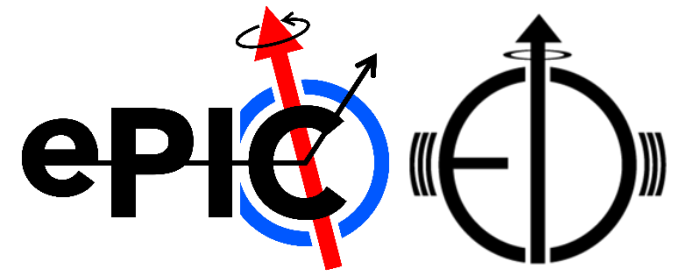
- **5 or 6 RSUs.**
- **Single data link.**
- Multiplexed slow controls.
- Serial powering.

EIC-LAS

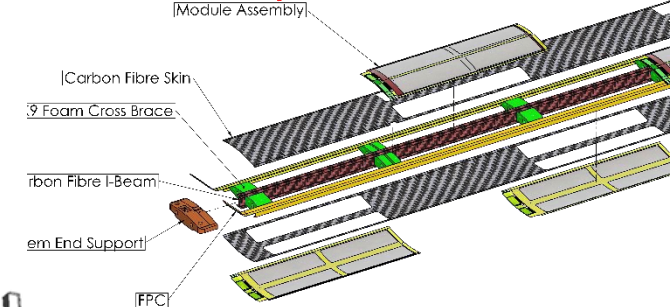
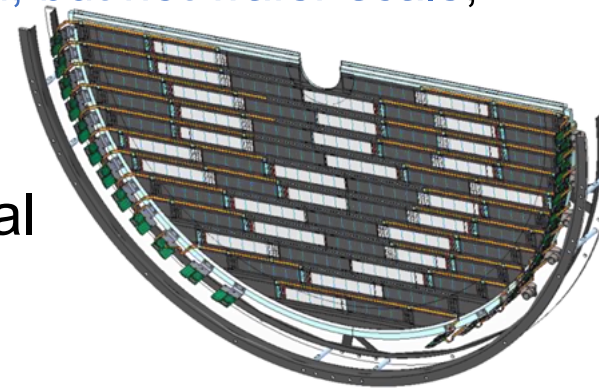
Ancillary ASIC



Outer barrel and endcap disks



- EIC Large Area Sensor optimised for high yield, low cost, large area coverage.
 - Modification of the ITS3 sensor; LAS stitched, but not wafer scale; planned modification(s) in the periphery to reduce number of readout links.
- Lightweight mechanical supports (staves, disks) with integrated cooling and electrical interfaces.
- Large lever arm with high precision measurements.
 - Improve momentum resolution.
 - Maximise acceptance at high eta.
- Disk inner opening defined by beam pipe bake-out constraints and off-centred, where beam pipe diverges.

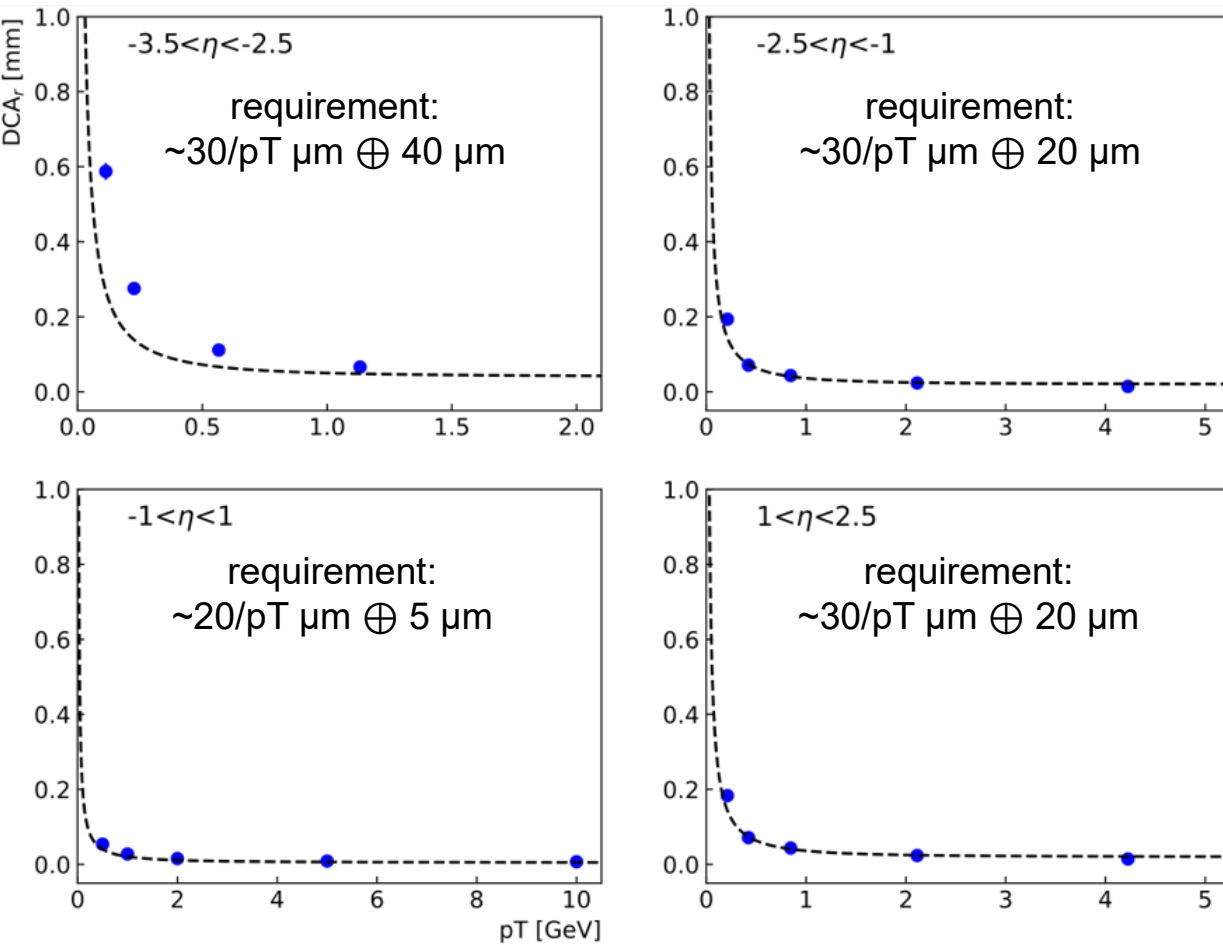
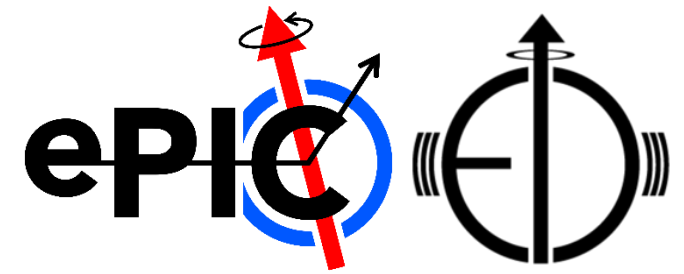


| OB | r (mm) | L (mm) | x/X ₀ (%) |
|----|--------|--------|----------------------|
| L3 | 270 | 540 | 0.25 |
| L4 | 420 | 840 | 0.55 |

| Disks | +z (mm) | -z (mm) | r_out (mm) | x/X ₀ (%) |
|-------|---------|---------|------------|----------------------|
| D0 | 250 | -250 | 240 | 0.25 |
| D1 | 450 | -450 | 420 | 0.25 |
| D2 | 700 | -650 | 420 | 0.25 |
| D3 | 1000 | -850 | 420 | 0.25 |
| D4 | 1350 | -1020 | 420 | 0.25 |

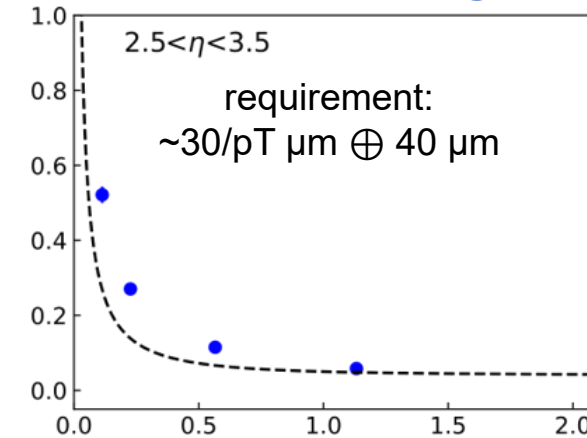


Tracking performance



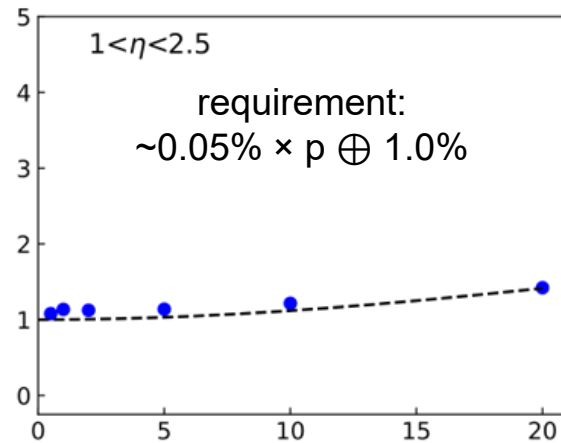
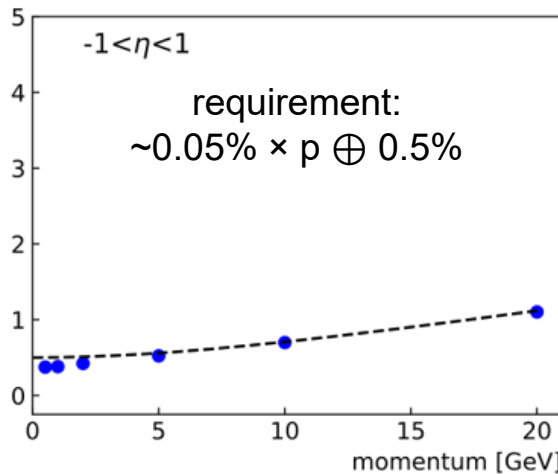
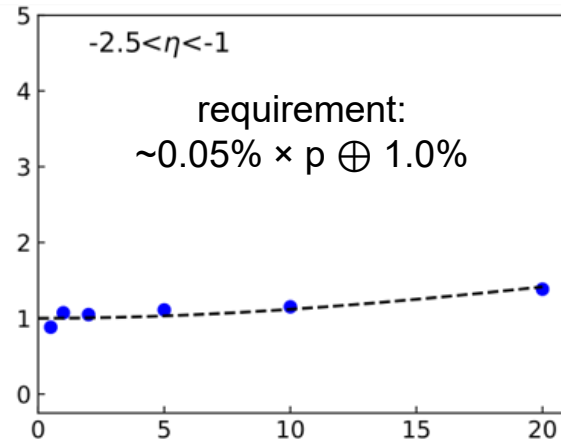
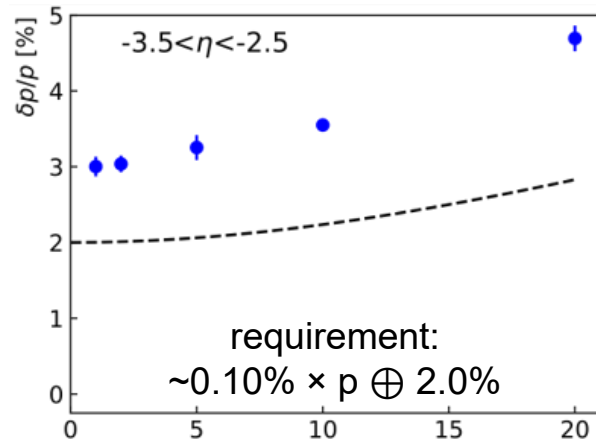
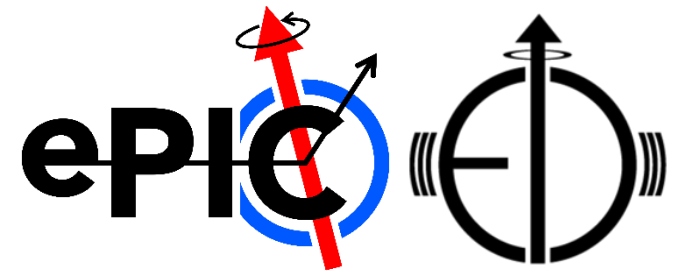
Requirements on transverse pointing resolution met in the central region and at mid-pseudo rapidity, with good agreement at large eta.

--- PWG Requirements
● ePIC 24.10

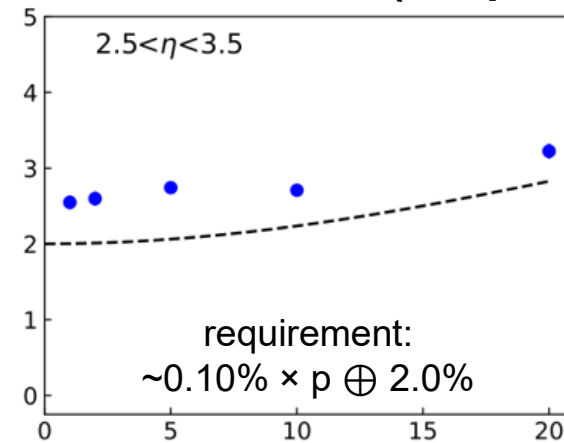


preliminary

Tracking performance



--- PWG Requirements
● ePIC 24.10



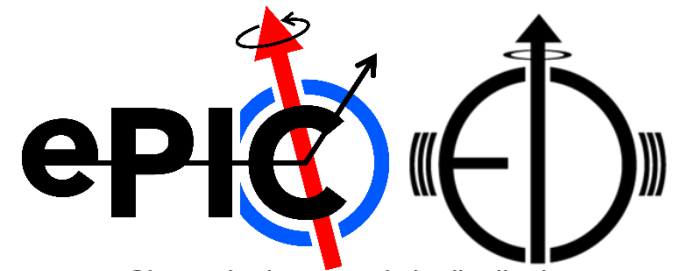
Requirements on relative momentum resolution **met** in the central region and mid-pseudo rapidity, but **challenging at large eta** (especially e-going side).

preliminary

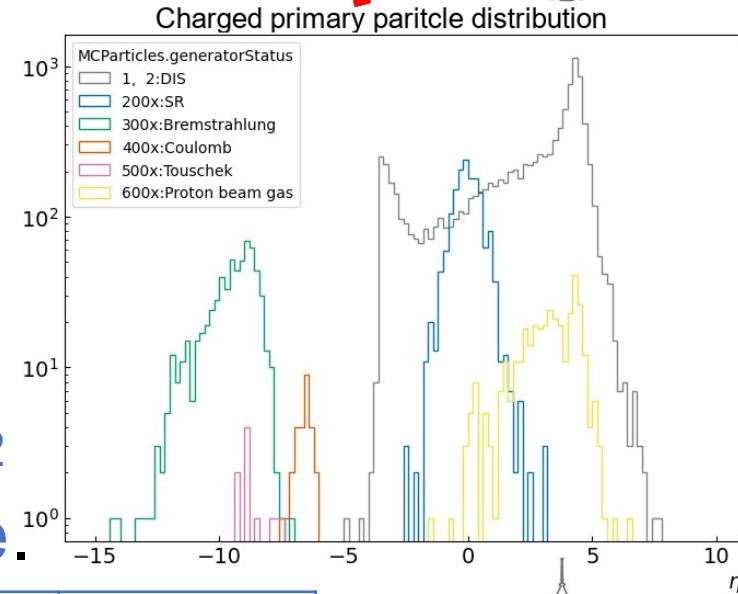


UNIVERSITY OF BIRMINGHAM

Hit rates in the SVT



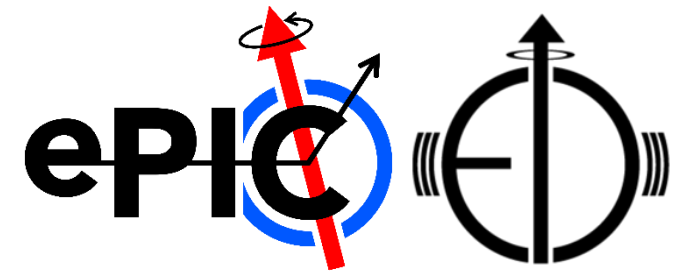
- Background event dominate the hit rates in the SVT.
- Example study; 18×275 GeV DIS e+p events mixed with proton/electron beam gas and synchrotron radiation.
- Each tracking layer is segmented with a 2×2 cm² grid to approximate the active pixel array structure.



| IB, OB | max hits /(2×2 cm ² ms) | average hits /(2×2 cm ² ms) | EE | max hits /(2×2 cm ² ms) | average hits /(2×2 cm ² ms) | HE | max hits /(2×2 cm ² ms) | average hits /(2×2 cm ² ms) |
|--------|---------------------------------------|---|-----|---------------------------------------|---|-----|---------------------------------------|---|
| L0 | 2365 | 1105 | ED0 | 729 | 105 | HD0 | 553 | 97 |
| L1 | 958 | 493 | ED1 | 657 | 61 | HD1 | 541 | 41 |
| L2 | 197 | 107 | ED2 | 620 | 59 | HD2 | 110 | 12 |
| L3 | 45 | 16 | ED3 | 176 | 40 | HD3 | 132 | 4 |
| L4 | 9 | 3 | ED4 | 23 | 7 | HD4 | 79 | 3 |

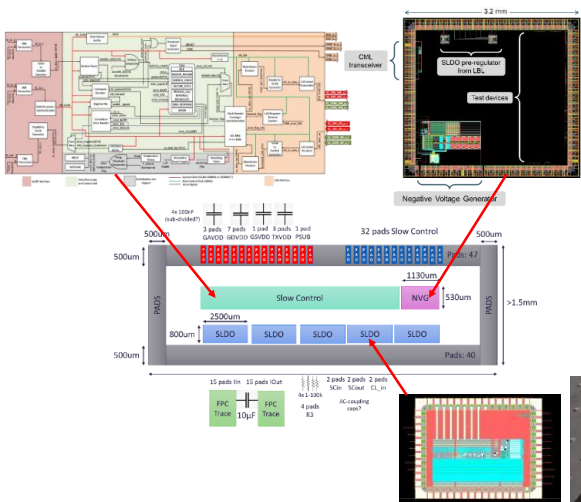


Ongoing activities

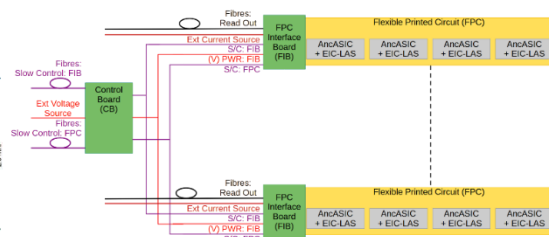


- Developments targets **low mass technological solutions** to satisfy the **physics requirements** and achieve **tight integration** of the different SVT regions.

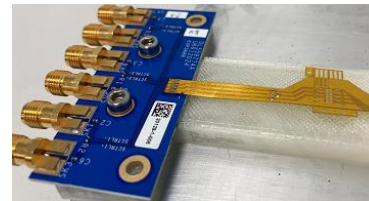
Ancillary ASIC development



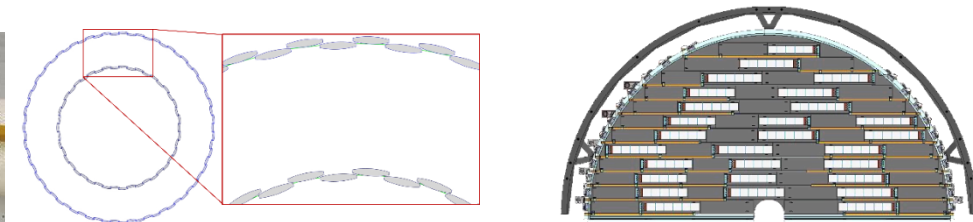
Readout chains



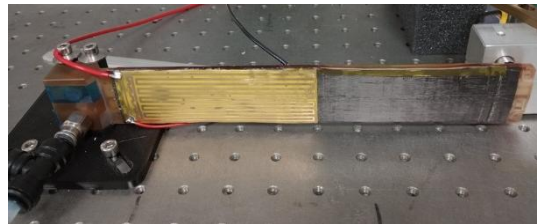
Low-mass electrical interfaces



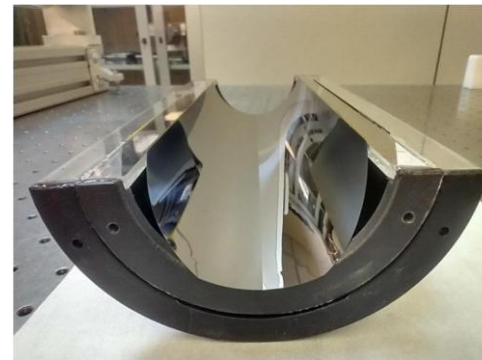
Design of OB and endcap disks



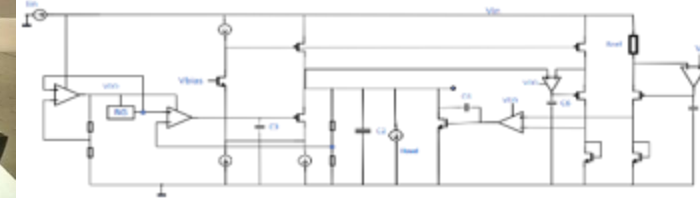
Air cooling through support structures



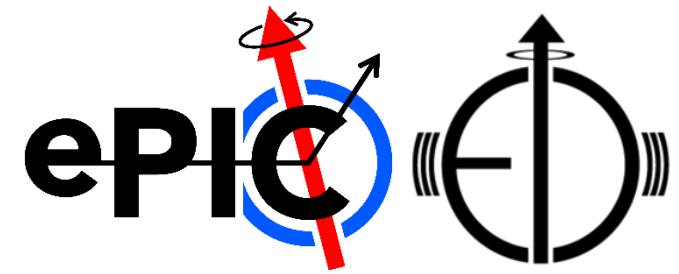
Bending of large 50 μm silicon structures



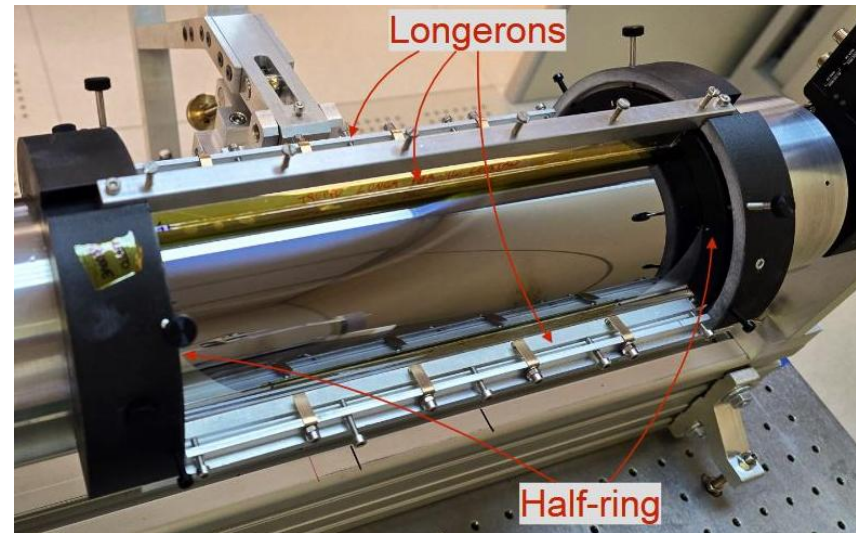
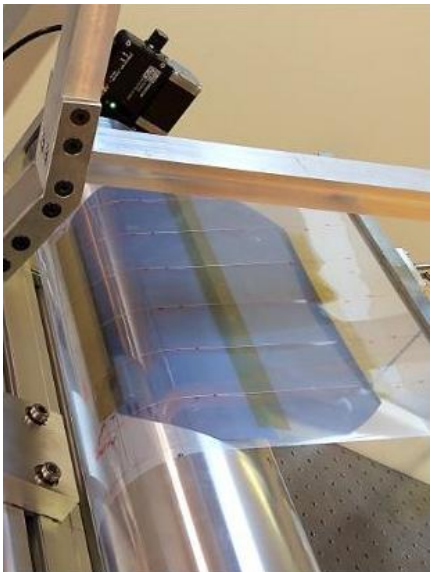
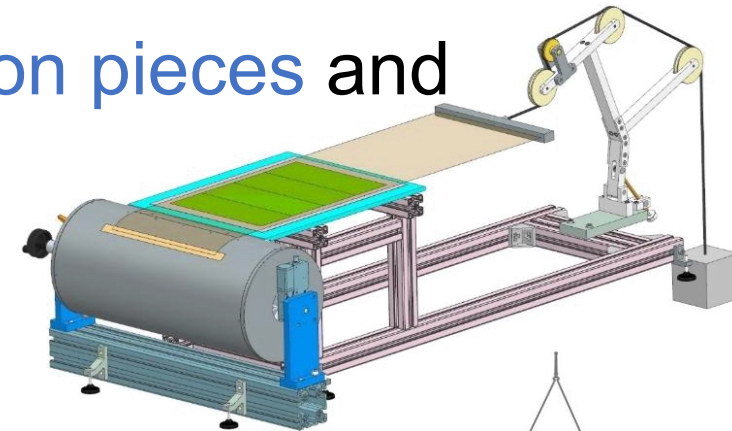
Serial powering



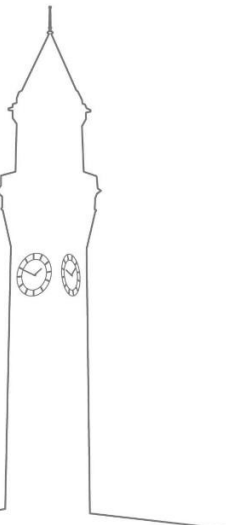
IB: Bending large scale sensors



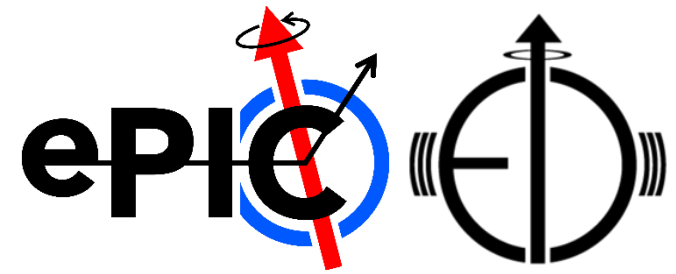
- Larger radii than ITS3.
- Need to **bend multiple sensors together**.
- Initial trials performed on joining **two dummy silicon pieces** and bending to required radii.



| IB | MOSAIX /sensor | Diced W (mm) | Diced L (mm) |
|----|----------------|--------------|--------------|
| L0 | 3 | 58.7 | 266 |
| L1 | 4 | 78.3 | 266 |
| L2 | 5 | 97.8 | 266 |



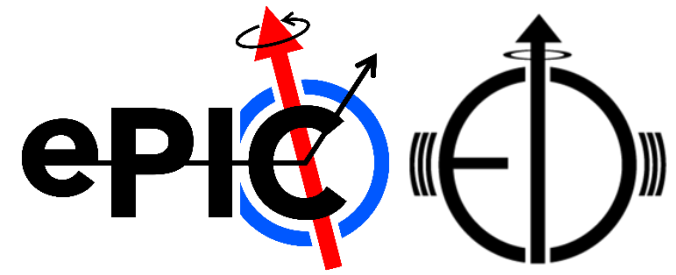
Integrated mechanics and cooling



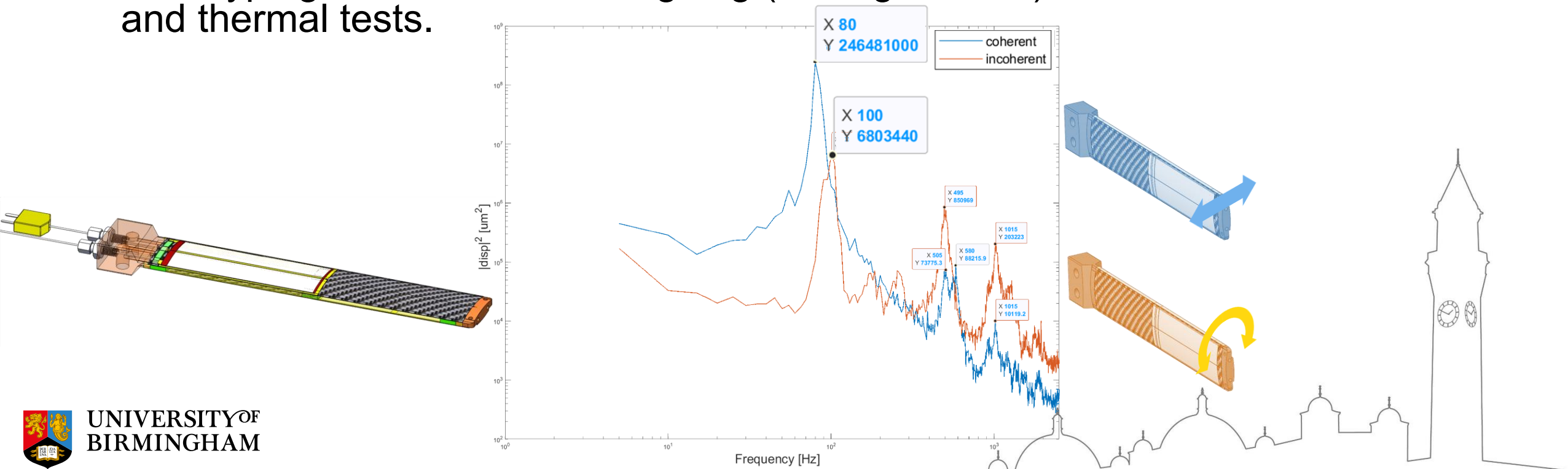
- The SVT will operate at **room temperature** with an estimated total sensor power consumption of **$\mathcal{O}(10\text{kW})$** (incl. overhead for powering and data transmission).
- Preferred cooling solution for the SVT is **air cooling**.
 - Baseline for IB, OB and disks (OB and disks also considering strategic liquid cooling).
 - Ongoing studies of **airflow internal to the support structure for OB and disks**.



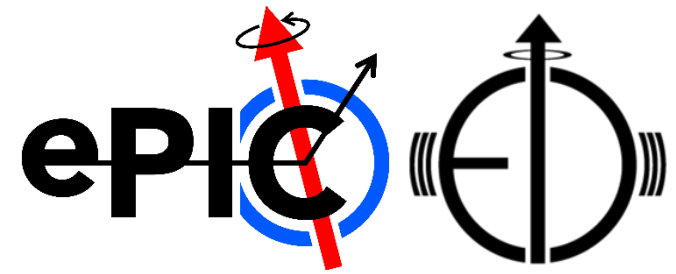
OB: Air flow through stave



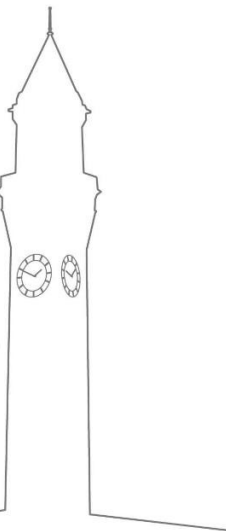
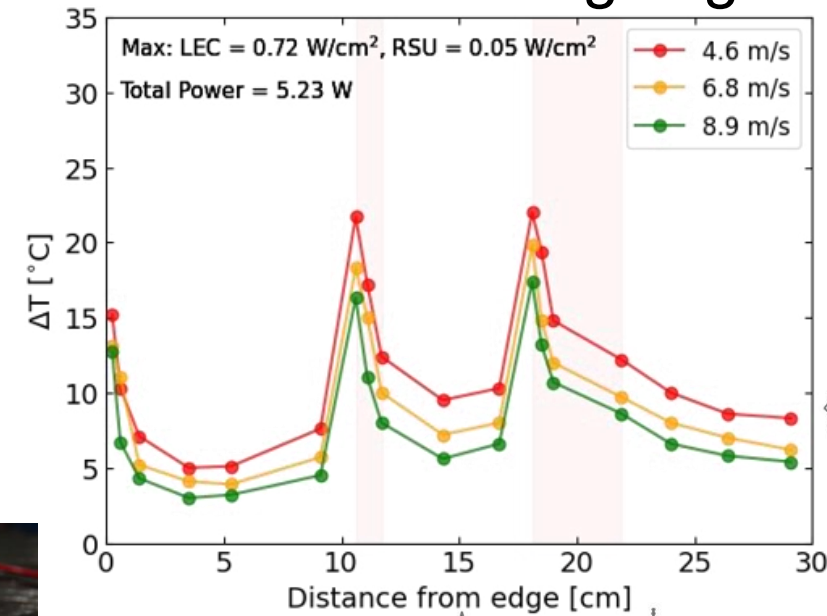
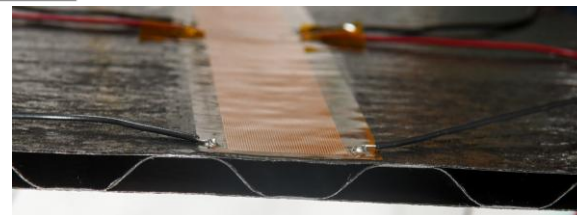
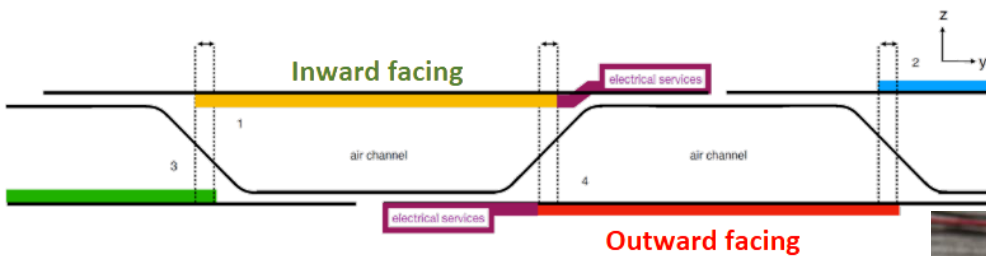
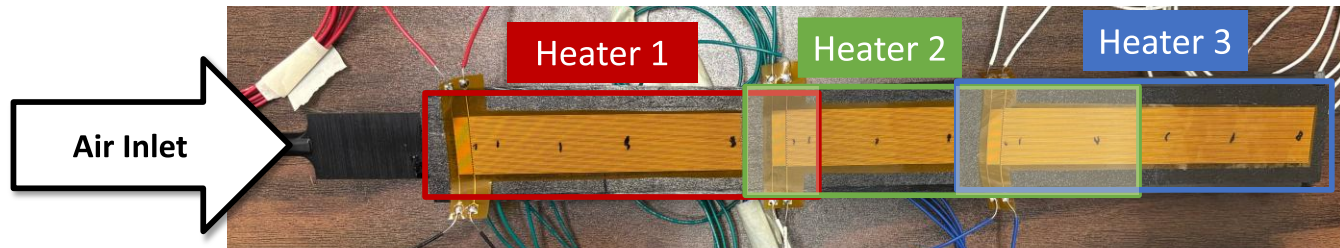
- EIC-LAS **curved** (convex) on both sides of a carbon foam/fibre stave structure.
- Support and electrical services around the sensors; **stave core is the air channel**.
- Prototyping of test structure ongoing (1/4 length stave); utilised for mechanical and thermal tests.



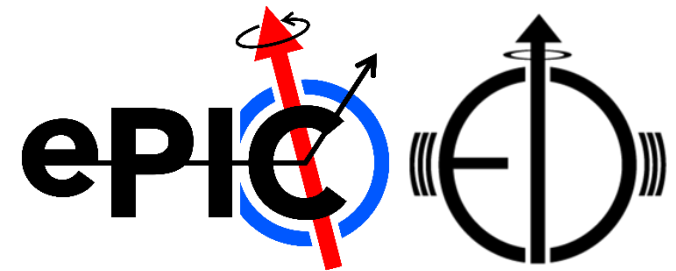
Disks: Air flow through corrugation



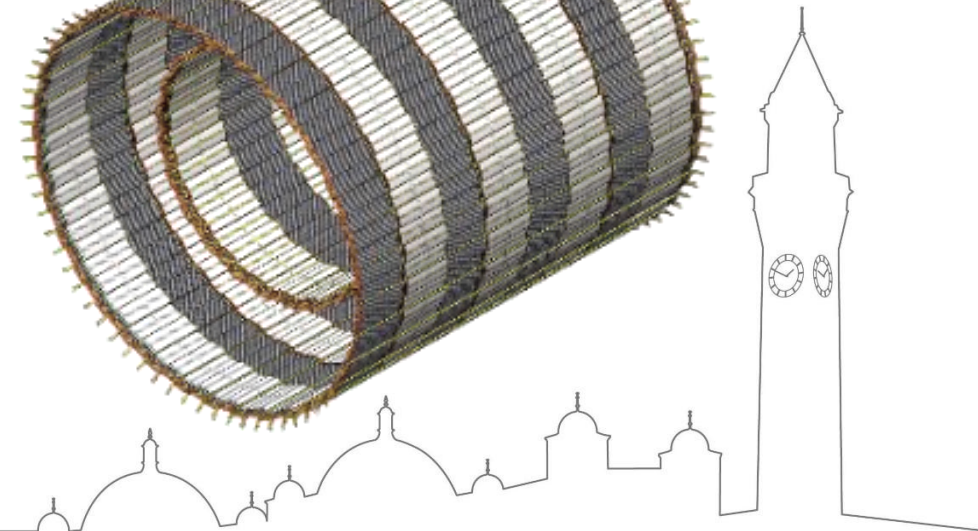
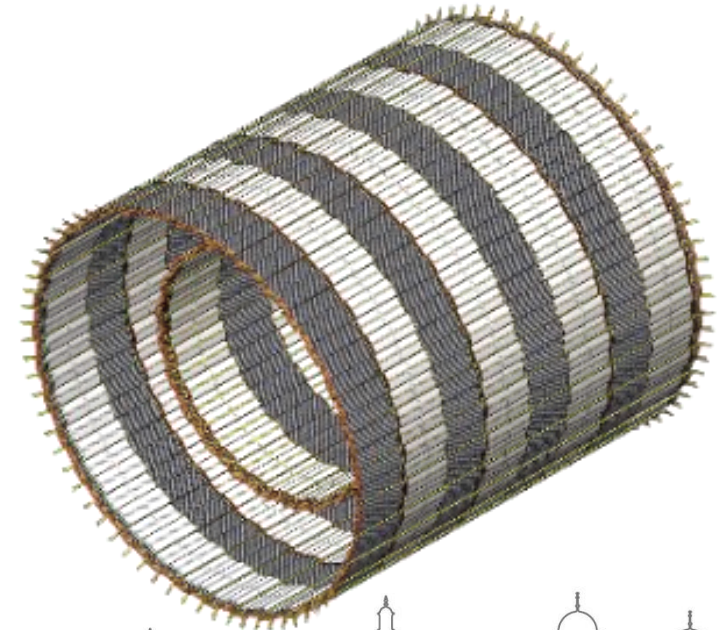
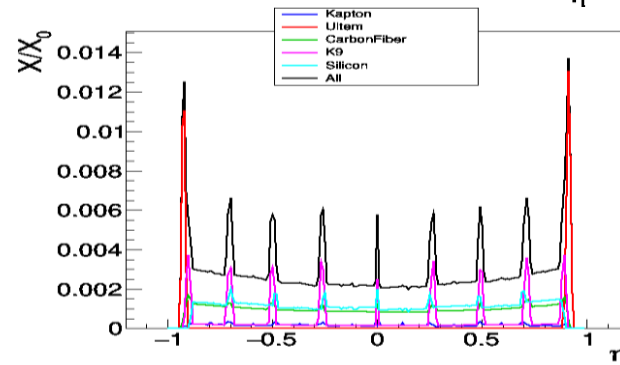
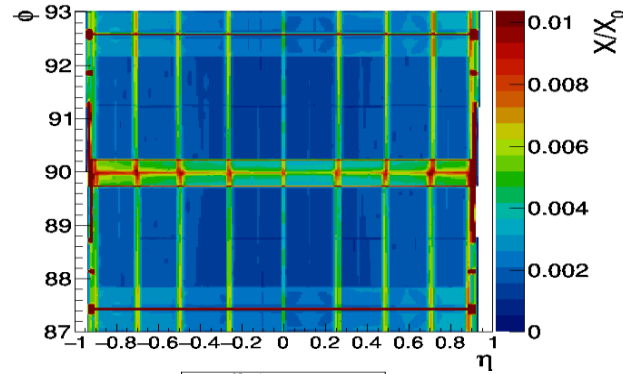
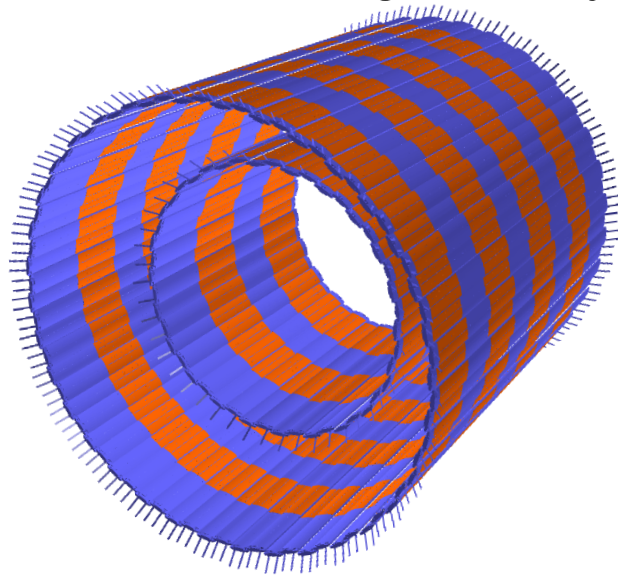
- EIC-LAS on **both sides** of corrugated support structure on carbon fibre sheets.
- Support and space for electrical services between modules; channel for air flow.
- Prototyping of test structures; mechanical and thermal tests are ongoing.



CAD geometry in simulations



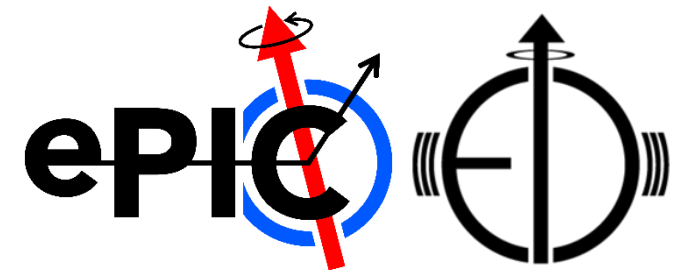
- Scripts to **convert a CAD model (.step)** to a geometry for simulation (.gdml).
- Comparison tool to cross-check standard simulation geometry.
 - Much slower to run (very complex geometry, many vertices).
 - Planned to inform **accurate material values and locations** for a comparable simulation geometry.



UNIVERSITY OF
BIRMINGHAM

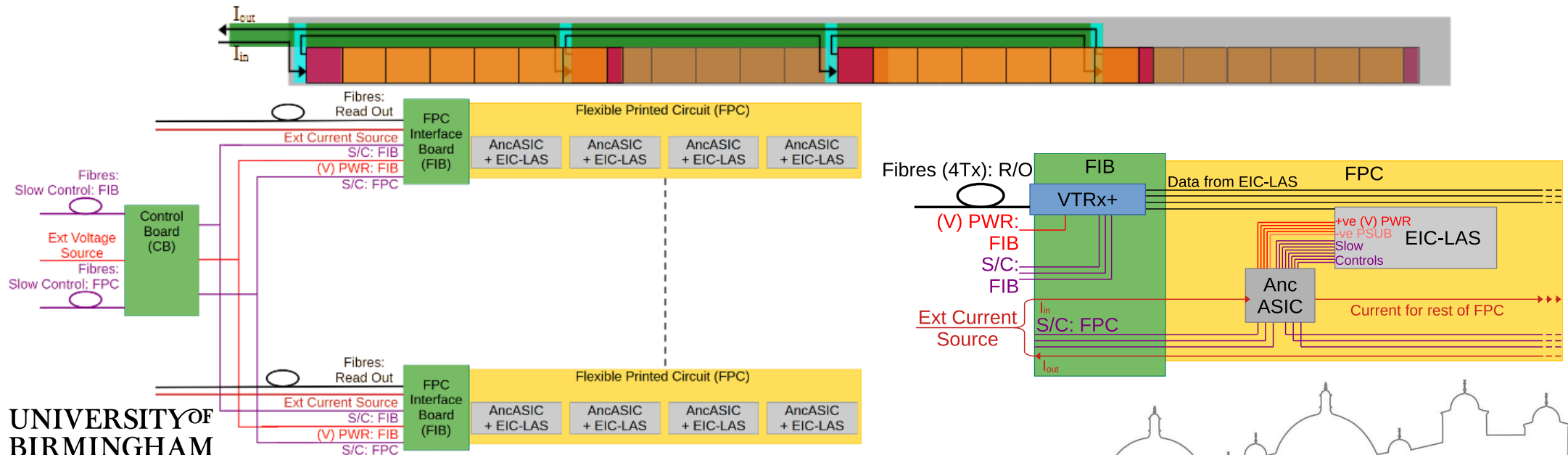
preliminary

Services: Material reduction

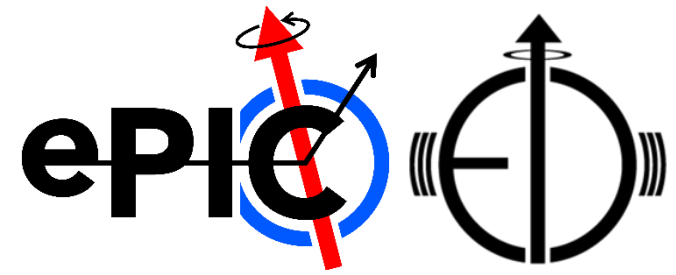


Considerations have been made to keep the service material to a minimum.

- Serial powering of sensors (OB and disks).
- All data transmission (readout and S/Cs) over fibre optics.
- Aggregating EIC-LAS S/C into a single I²C bus per flexible printed circuit.
- Consolidation of S/C related boards to minimise numbers.



Conclusions



- The EIC will be a **world's unique facility** to continue exploration of strongly interacting matter using DIS, commencing operation in the mid 2030s.
- The ePIC Silicon Vertex Tracker is a **large, thin, MAPS-based detector**, with **very demanding requirements** for precision measurements and integration.
- **Synergies with ALICE ITS3 developments + large programme of dedicated development** on a low-mass detector with integrated mechanical and cooling structures, and multifaceted service reductions.

It is not too late to get involved!

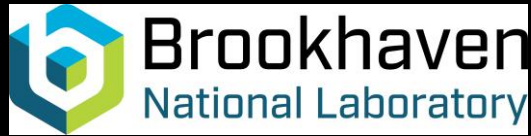




UNIVERSITY OF BIRMINGHAM



ePIC Silicon Vertex Tracker Detector Subsystem Collaboration



Detector Subsystem Leader: Ernst Sichterman (LBNL)
Detector Subsystem Technical Coordinator: Laura Gonella (Trieste)
Detector Subsystem Technical Coordinator: Georg Viehhauser (Oxford)